

## Features

- Low profile - typical height 1.1 mm
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- High temperature soldering guaranteed: 260°C/10 seconds
- Halogen-free according to IEC 61249-2-21 definition

## Applications

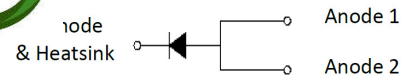
For low voltage high frequency inverters, DC/DC converters and polarity protection applications.

## Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	45	V
Maximum RMS Voltage	$V_{RMS}$	31.5	V
Maximum DC Blocking Voltage	$V_{DC}$	45	V
Maximum Average Forward Rectified Current	$I_{F(AV)}^{1)}$	6.0	A
	$I_{F(AV)}^{2)}$	15.0	
Peak Forward Surge Current (8.3ms single half sine-wave superimposed on rated load)	$I_{FSM}$	300	A
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$



Package:  
eSGC (TO-277)



Schematic Diagram

## Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Typ.	Max.	Unit	
Maximum Instantaneous Forward Voltage	$I_F=1\text{A}$	$T_A=25^\circ\text{C}$	$V_F$	0.30	0.32	V
	$I_F=15\text{A}$			0.44	0.47	
	$I_F=1\text{A}$	$T_A=85^\circ\text{C}$	0.22	0.27		
	$I_F=15\text{A}$		0.43	0.45		
	$I_F=1\text{A}$	$T_A=125^\circ\text{C}$	0.17	0.20		
	$I_F=15\text{A}$		0.42	0.45		
Maximum DC Reverse Current at Rated Blocking Voltage	Rated $V_R$	$I_R$	$T_A=25^\circ\text{C}$	0.08	0.2	mA
			$T_A=85^\circ\text{C}$	3.5	8	
			$T_A=125^\circ\text{C}$	25	35	
Junction Capacitance	4.0 V, 1 MHz	$C_J$	0.95		nF	
Typical Thermal Resistance	Junction to Ambient	$R_{\theta JA}^{1)}$	72		$^\circ\text{C/W}$	
	Junction to Mount	$R_{\theta JM}^{2)}$	1		$^\circ\text{C/W}$	

### Notes

1) Thermal resistance  $R_{\theta JA}$  is junction to ambient. Free air, mounted on P C B with recommended copper pad area, 2 OZ, FR4

2) Thermal resistance  $R_{\theta JM}$  is junction to mount, mounted on P.C.B with 30\*30mm copper pad area

## Ratings and Characteristics Curves ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

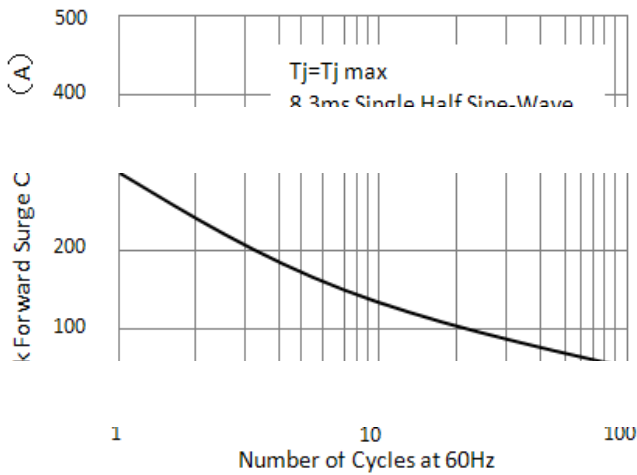


Figure 1. Maximum Non-Repetitive Peak Forward Surge Current

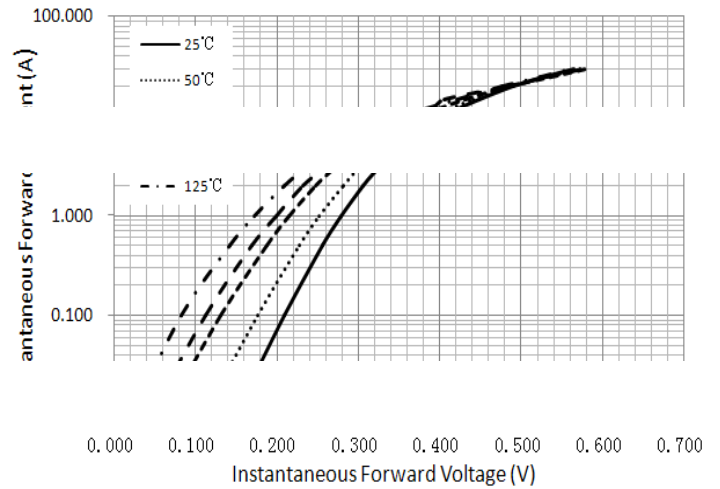


Figure 2. Typical Instantaneous Forward Characteristics

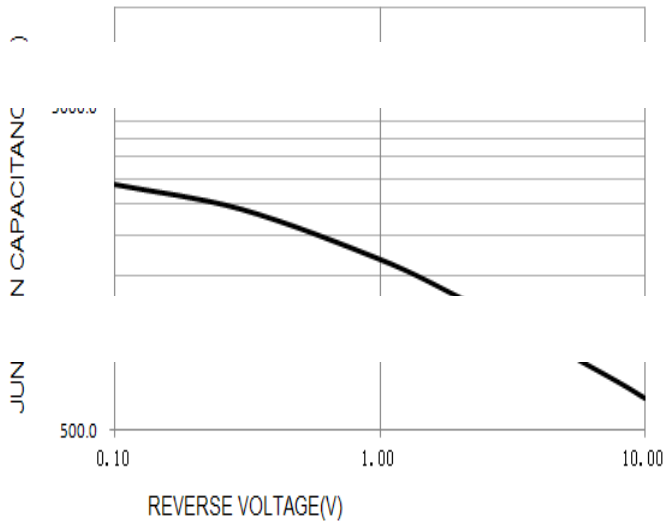


Figure 3. Typical Junction Capacitance

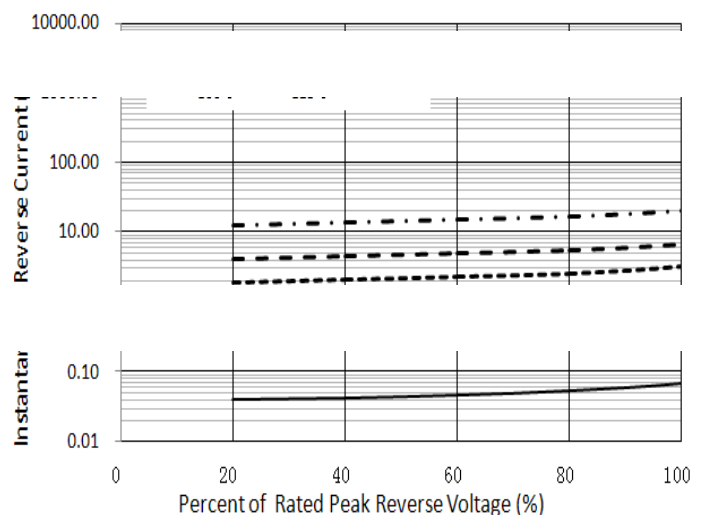


Figure 4. Typical Reverse Characteristics

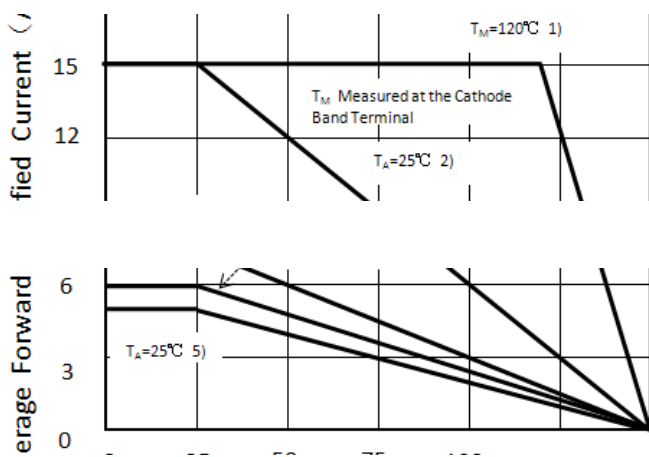


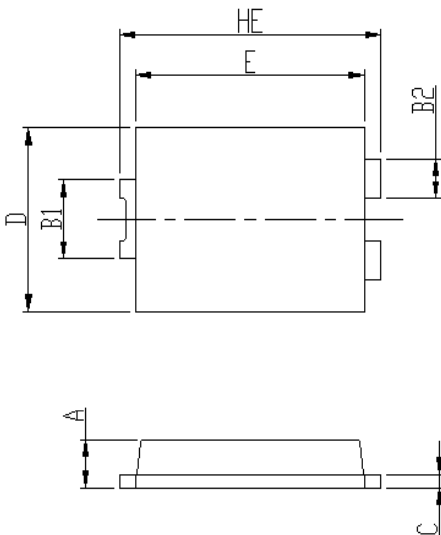
Figure 5. Forward Current Derating Curve

### Notes

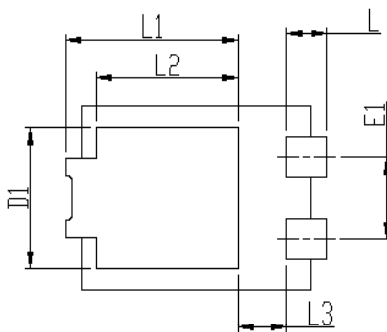
- 1) Mounted on P.C.B with 30\*30mm copper pad area
- 2) Mounted on P.C.B with 30\*30mm copper pad area ( $R_{\theta JA} = 27^\circ\text{C/W}$ )
- 3) Mounted on P.C.B with 30\*30mm copper pad area FR4 PCB ( $R_{\theta JA} = 37^\circ\text{C/W}$ )
- 4) Free air, Mounted on recommended copper pad area FR4 PCB ( $R_{\theta JA} = 72^\circ\text{C/W}$ )
- 5) Free air, Mounted on recommended copper pad area FR4 PCB ( $R_{\theta JA} = 82^\circ\text{C/W}$ )

## Package Outline Dimensions

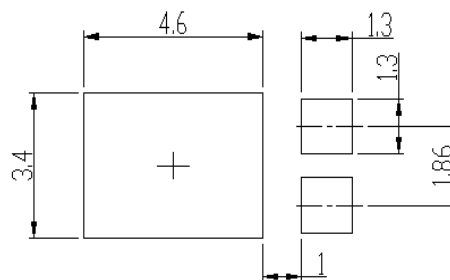
### eSGC (TO-277)



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
HE	6.4	6.6	0.252	0.260
E	5.6	5.8	0.220	0.228
D	4.1	4.3	0.161	0.169
B1	1.7	1.9	0.067	0.075
B2	0.8	1	0.031	0.039
A	1.05	1.2	0.041	0.047
C	0.3	0.4	0.012	0.016
L	0.85	1.1	0.033	0.043
L1	4.2	4.4	0.165	0.173
L2	3.52 Typ.		0.139 Typ.	
L3	1.1	1.4	0.043	0.055
D1	3	3.3	0.118	0.130
E1	1.86 Typ.		0.073 Typ.	



### Soldering footprint



## Packing Information

### Packing quantities

5000 pcs/Reel, 12 mm Tape, 13" Reel

### Tape & Reel Specification

